Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: http://www.renesas.com

April 1st, 2010 Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

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Silicon NPN Epitaxial

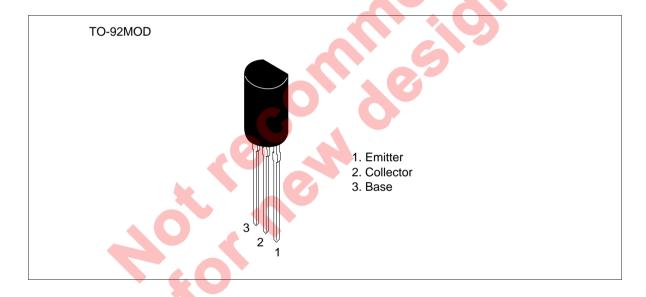


ADE-208-1159 (Z) 1st. Edition Mar. 2001

Application

Low frequency high voltage amplifier

Outline



Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

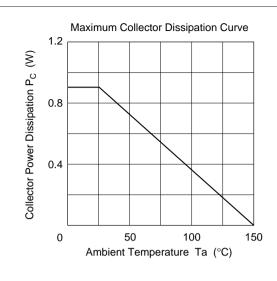
Item	Symbol	2SA1868	2SA1869	Unit
Collector to base voltage	V_{CBO}	160	200	V
Collector to emitter voltage	V_{CEO}	160	200	V
Emitter to base voltage	V_{EBO}	5	5	V
Collector current	I _c	100	100	mA
Collector power dissipation	P _c	0.9	0.9	W
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	_55 to +150	°C

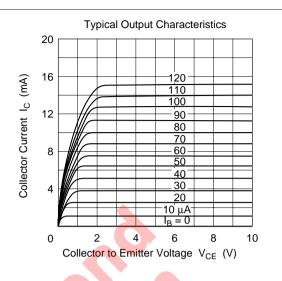
Electrical Characteristics ($Ta = 25^{\circ}C$)

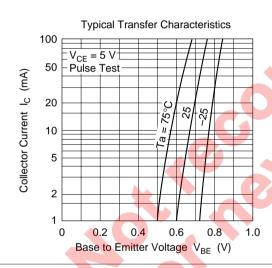
Item		Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	2SD1868	$V_{(BR)CBO}$	160	_	4	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
	2SD1869	_	200				
Collector to emitter breakdown voltage	2SD1868	$V_{(BR)CEO}$	160		-	V	$I_C = 1 \text{ mA}, R_{BE} = \infty$
	2SD1869		200				
Emitter to base brea voltage	ıkdown	$V_{(BR)EBO}$	5	-		V	$I_{E} = 10 \ \mu A, \ I_{C} = 0$
Collector cutoff current	2SD1868	I _{CBO}	_		10	μΑ	$V_{CB} = 140 \text{ V}, I_{E} = 0$
	2SD1869		A				$V_{CB} = 160 \text{ V}, I_{E} = 0$
DC current transfer	ratio	h _{FE1} *1	60	_	320		$V_{CE} = 5 \text{ V}, I_{C} = 10 \text{ mA}$
		h _{FE2}	30	_	_		$V_{CE} = 5 \text{ V}, I_{C} = 1 \text{ mA}$
Base to emitter volta	age	V_{BE}	_	_	1.5	V	$V_{CE} = 5 \text{ V}, I_{C} = 10 \text{ mA}$
Collector to emitter s voltage	saturation	V _{CE(sat)}	_	_	2	V	$I_{\rm C} = 30$ mA, $I_{\rm B} = 3$ mA
Gain bandwidth prod	duct	f _⊤	_	140	_	MHz	$V_{CE} = 5 \text{ V}, I_{C} = 10 \text{ mA}$
Collector output cap	acitance	C _{ob}		3.8		pF	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$

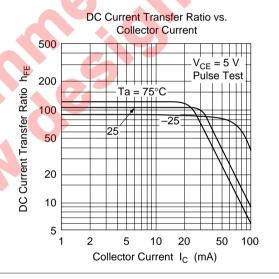
Note: 1. The 2SD1868 and 2SD1869 are grouped by h_{FE1} as follows.

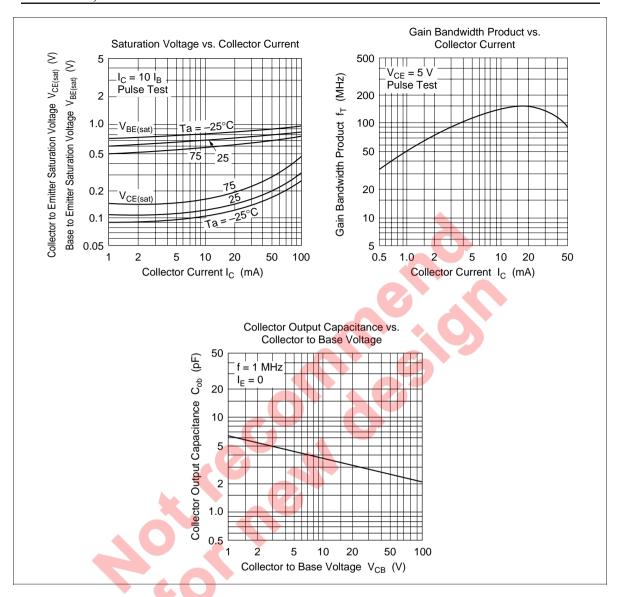
Grade	В	С	D
h _{FE1}	60 to 120	100 to 200	160 to 320



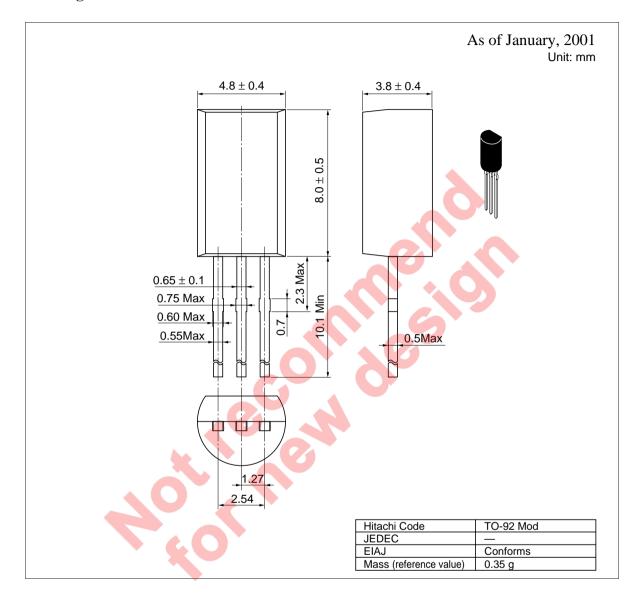








Package Dimensions



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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Germany

Hitachi Europe GmbH Electronic Components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Fax: <1>(408) 433-0223 Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00

> Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom

Tel: <44> (1628) 585000 Fax: <44> (1628) 585160 Hitachi Asia Ltd. Hitachi Tower 16 Collyer Quay #20-00, Singapore 049318 Tel: <65>-538-6533/538-8577 Fax: <65>-538-6933/538-3877 URL: http://www.hitachi.com.sg

Hitachi Asia Ltd. (Taipei Branch Office) 4/F, No. 167, Tun Hwa North Road, Hung-Kuo Building, Taipei (105), Taiwan Tel: <886>-(2)-2718-3666

Fax: <886>-(2)-2718-8180 Telex: 23222 HAS-TP URL: http://www.hitachi.com.tw Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road Tsim Sha Tsui, Kowloon, Hong Kong

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